



Set -1 of 1

RECEIVED		Atty. Docket No. 3693-011770	Serial No. 09/985,728
LIST OF CITATIONS BY APPLICANT - 4		Applicants Lawrence N. Crane et al.	
(Use several sheets if necessary)		Filing Date November 6, 2001	Group Art 2811

U.S. PATENT DOCUMENTS

2827

Exam. Init.		Document No.	Date	Name	Class	Subclass	Filing Date if appropriate
AC	AA	5,512,613	04/30/96	Afzali-Ardakani et al.	523	443	
AC	AB	5,560,934	10/01/96	Afzali-Ardakani et al.	424	497	
AC	AC	5,760,337	06/02/98	Iyer et al.	174	52.2	
AC	AD	5,872,158	02/16/99	Kuczynski	522	182	
AC	AE	5,932,682	08/03/99	Buchwalter et al.	528	94	
AC	AF	5,948,922	09/07/99	Ober et al.	549	547	
AC	AG	5,973,033	10/26/99	Ober et al.	523	443	
AC	AH	5,985,043	11/16/99	Zhou et al.	148	24	
AC	AI	5,985,456	11/16/99	Zhou et al.	428	414	
AC	AJ	6,121,689	09/19/00	Capote et al.	257	783	
AC	AK	6,297,560 B1	10/02/01	Capote et al.	257	778	

FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subclass	Translation Yes	No
AC	AL	98/31738	07/23/98	WIPO				
AC	AM	00/56799	09/28/00	WIPO				
AC	AN	00/79582	12/28/00	WIPO				
AC	AO	93226416	09/03/93	JAPAN			Machine	
	AP							

OTHER CITATIONS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AQ	
	AR	
	AS	

Examiner <i>Alvin Chamberlain</i>	Date Considered 3/9/03
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE STATEMENT FORM (PTO 1449)

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
3693-011770 (LC-413)SERIAL NO.
09/985,728INFORMATION DISCLOSURE STATEMENT
STATEMENT BY APPLICANT

(Use several sheets if necessary)

APPLICANT(S)
Lawrence N. CRANE et al.FILED
November 6, 2001

GROUP ART UNIT

2811 2827

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
AC	AI	5 8 1 4 4 0 1	09/29/1998	Gamota et al.	428	343	
	AJ						
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
AC	AL	9 9 0 4 4 3 0	01/28/1999	WO			
AC	AM	9 9 5 6 3 1 2	11/04/1999	WO			
AC	AN	0 8 0 8 8 4 64	08/30/1996	JP			Abstract
	AO						
	AP						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AC	AQ	Rindusit et al., "Development of new class of electronic packaging materials based on ternary systems of benzoxazine, epoxy, and phenolic resins" Polymer, Elsevier Science Publishers B.V., GB, Vol. 41, No. 22, October 2000, Pages 7941-7949
AC	AR	Fan et al., "Adhesion comparison between thermosetting and thermoplastic resin systems based on poly(bisphenol A-co-epichlorohydrin) chemistry", 4 th International Conference on Adhesive Joining and Coating Technology in Electronics Manufacturing, Pages 243-247
AC	AS	Johnson et al., "Reflow-curable polymer fluxes for flip chip encapsulation", Multichip Modules and High Density Packaging, 1998, pages 41-46

EXAMINER

Adams Chamberliss

DATE CONSIDERED

3/9/03

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